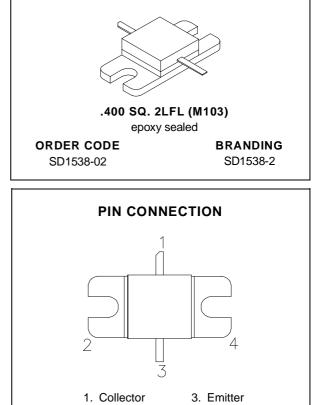


# SD1538-02

# RF & MICROWAVE TRANSISTORS AVIONICS APPLICATIONS

- DESIGNED FOR HIGH POWER PULSED IFF, DME, TACAN APPLICATIONS
- 200 WATTS (typ.) IFF 1030 1090 MHz
- 150 WATTS (min.) DME 1025 1150 MHz
- 140 WATTS (typ.) TACAN 960 1215 MHz
- 7.8 dB MIN. GAIN
- REFRACTORY GOLD METALLIZATION
- EMITTER BALLASTING AND LOW THERMAL RESISTANCE FOR RELIABILITY AND RUGGEDNESS
- 30:1 LOAD VSWR CAPABILITY AT SPECIFIED OPERATING CONDITIONS
- INPUT/OUTPUT MATCHED, COMMON BASE CONFIGURATION



4. Base

2. Base

#### DESCRIPTION

The SD1538-02 is a gold metallized silicon, NPN power transistor designed for applications requiring high peak power and low duty cycles such as IFF, DME and TACAN. The SD1538-02 is packaged in a metal/ceramic package with internal input/output matching resulting in improved broadband performance and a low thermal resistance.

#### **ABSOLUTE MAXIMUM RATINGS** ( $T_{case} = 25^{\circ}C$ )

Symbol	Parameter	Value	Unit	
V <sub>CBO</sub>	Collector-Base Voltage	65	V	
V <sub>CES</sub>	Collector-Emitter Voltage	65	V	
V <sub>EBO</sub>	Emitter-Base Voltage	3.5	V	
lc	Device Current	11.0	А	
PDISS	Power Dissipation	583	W	
TJ	Junction Temperature	+200	°C	
T <sub>STG</sub>	Storage Temperature	– 65 to +150	°C	

#### THERMAL DATA

R <sub>TH(j-c)</sub>	Junction-Case Thermal Resistance	0.30	°C/W	
November 1992			1/5	

# SD1538-02

### **ELECTRICAL SPECIFICATIONS** (Tcase = 25°C)

STATIC

Symbol	Test Conditions	Value			Unit		
		Min.	Тур.	Max.	Unit		
ВVсво	$I_C = 10 mA$	$I_E = 0 m A$		65			V
BVCES	$I_C = 25 mA$	$V_{BE} = 0V$		65		_	V
BV <sub>EBO</sub>	$I_E = 5 m A$	$I_C = 0 m A$		3.5		_	V
ICES	$V_{CE} = 50V$	$I_E = 0 m A$			_	10	mA
hfe	$V_{CE} = 5V$	$I_C = 300 \text{mA}$		5		_	

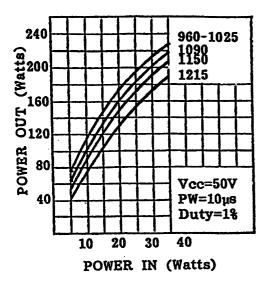
#### DYNAMIC

Symbol		Test Conditions		Value		
Symbol	Тур.			Max.	Unit	
	Роит	$f = 1025 - 1150 MHz P_{IN} = 25.0 W V_{CE} = 50 V$	150	_		W
	GP	$f = 1025 - 1150 MHz P_{IN} = 25.0 W V_{CE} = 50 V$	7.8	_		dB

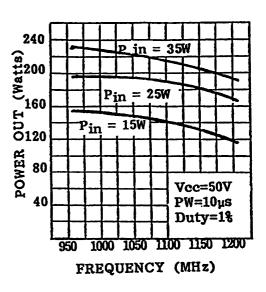
Note: Pulse Width =  $10\mu$ Sec, Duty Cycle = 1%This device is suitable for use under other pulse width/duty cycle conditions. Please contact the factory for specific applications assistance.

## **TYPICAL PERFORMANCE**

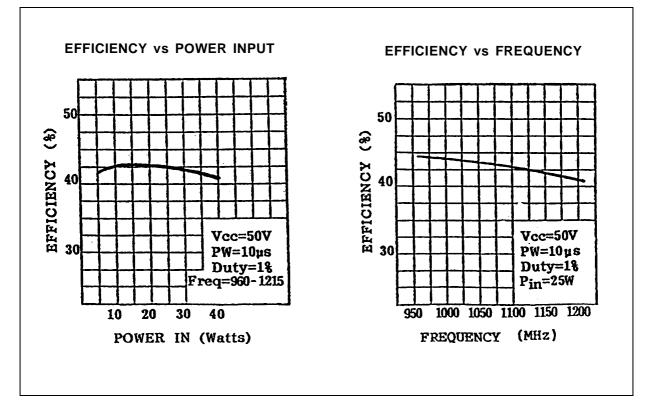
#### POWER OUTPUT vs POWER INPUT



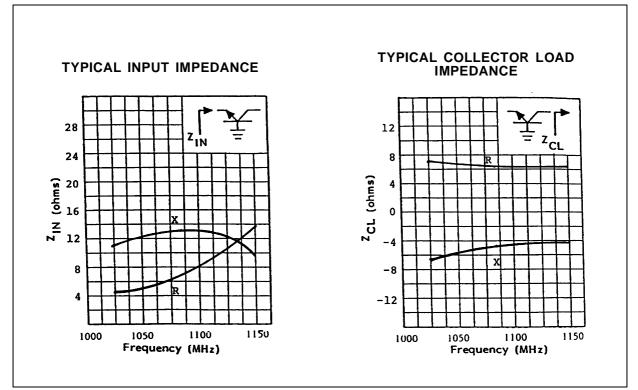
#### **POWER OUTPUT vs FREQUENCY**



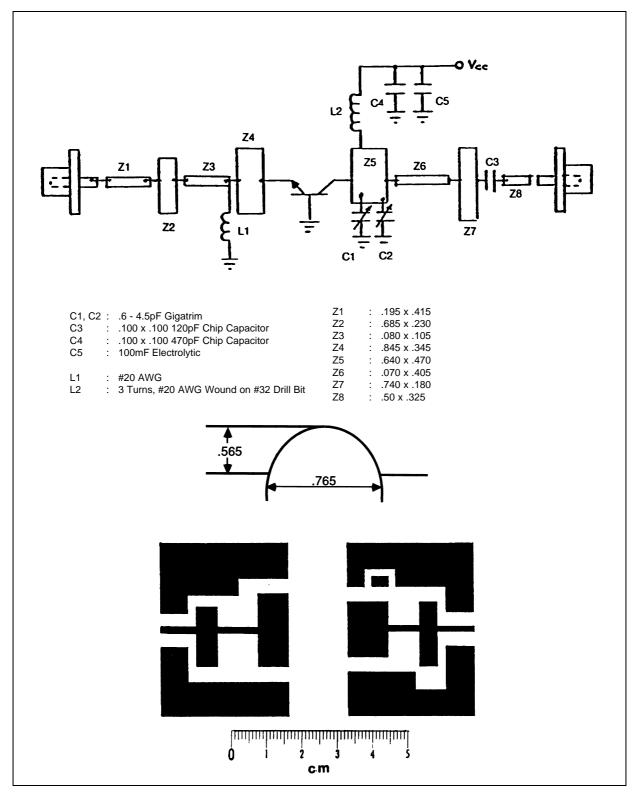
#### **TYPICAL PERFORMANCE (cont'd)**



**IMPEDANCE DATA** 



#### **TEST CIRCUIT AND PC BOARD LAYOUT**

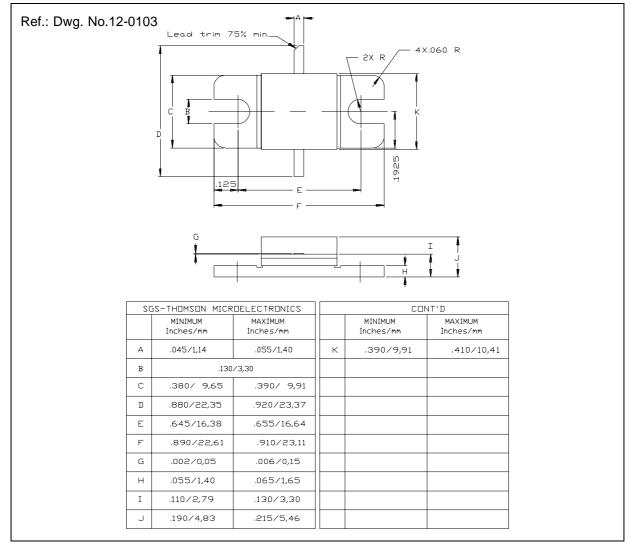


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57.

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# PACKAGE MECHANICAL DATA



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